

## 关键参数

## Key Parameters

|              |      |           |                 |
|--------------|------|-----------|-----------------|
| $V_{DSmax}$  |      | 1200      | V               |
| $R_{DS(on)}$ | Typ. | 80        | mΩ              |
| $I_D$        | Max. | 44        | A               |
| Die Size     |      | 3.43×3.43 | mm <sup>2</sup> |

## 特点

## Features

- 高开关频率 High Switching Frequency
- 低开关损耗 Low Switching Loss
- 软、快速开关 Soft, fast Switching
- 易并联使用 Easy Paralleling

## 电路结构

## Circuit Configuration

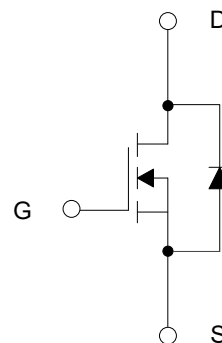


图 1. 电路结构

Fig. 1 Circuit configuration

## 最大额定值

## Maximum Ratings

| 符号<br>Symbol      | 参数名称<br>Parameter                                                                            | 测试条件<br>Test Conditions | 数值<br>Value | 单位<br>Unit |
|-------------------|----------------------------------------------------------------------------------------------|-------------------------|-------------|------------|
| $V_{DSmax}$       | 漏源极电压<br>Drain-source voltage                                                                |                         | 1200        | V          |
| $V_{GSS}$         | 栅源峰值电压<br>Gate-source voltage                                                                |                         | -6/+18      | V          |
| $I_D$             | 持续正向电流, 由 $T_{vj\ max}$ 限制<br>Continuous forward current, limited by $T_{vj\ max}$           |                         | 44          | A          |
| $I_{DM}$          | 最大重复正向电流, 由 $T_{vj\ max}$ 限制<br>Maximum repetitive forward current, limited by $T_{vj\ max}$ |                         | 88          | A          |
| $T_{vj\ max}$     | 最大允许结温<br>Max. Junction temperature                                                          |                         | 175         | °C         |
| $T_{vj(op)}$      | 工作结温<br>Operation junction temperature                                                       |                         | -55...+175  | °C         |
| $T_{Proc}^{(*1)}$ | 最大加工温度<br>Maximum processing temperature                                                     |                         | 325         | °C         |

**电特性值**
**Electrical Characteristics**

除非特别声明，否则  $T_{vj}=25\text{ }^{\circ}\text{C}$ 
 $T_{vj}=25\text{ }^{\circ}\text{C}$  unless otherwise stated

| 符号<br>Symbol        | 参数名称<br>Parameter                             | 测试条件<br>Test Conditions                                               | 最小值<br>Min. | 典型值<br>Typ. | 最大值<br>Max. | 单位<br>Unit |
|---------------------|-----------------------------------------------|-----------------------------------------------------------------------|-------------|-------------|-------------|------------|
| $I_{DSS}$           | 零栅压漏极电流<br>Zero gate voltage drain current    | $V_{GS}=0V, V_{DS}=V_{DSS}$                                           |             |             | 50          | $\mu A$    |
| $I_{GSS}$           | 栅极漏电流<br>Gate leakage current                 | $V_{GS}=V_{GSS}, V_{DS}=0V$                                           |             |             | 250         | nA         |
| $V_{GS(th)}^{(*2)}$ | 栅极-源极阈值电压<br>Gate threshold voltage           | $I_D=10\text{ mA}, V_{GS}=V_{DS}$                                     | 2.0         | 3.0         | 4.0         | V          |
| $R_{DS(on)}$        | 漏极-源极通态电阻<br>Drain-source on-state resistance | $V_{GS}=15V, I_D=20A$                                                 |             | 80          | 98          | m $\Omega$ |
|                     |                                               | $V_{GS}=15V, I_D=20A, T_{vj}=175\text{ }^{\circ}\text{C}$             |             | 107         |             | m $\Omega$ |
| $g_{fs}$            | 跨导<br>Forward transconductance                | $V_{DS}=20V, I_D=20A$                                                 |             | 11          |             | S          |
| $C_{iss}$           | 输入电容<br>Input capacitance                     | $V_{DS}=1000V, V_{GS}=0V,$<br>$f=100\text{ kHz}, V_{AC}=30\text{ mV}$ |             | 1390        |             | pF         |
| $C_{oss}$           | 输出电容<br>Output capacitance                    |                                                                       |             | 85          |             | pF         |
| $C_{rss}$           | 反向传输电容<br>Reverse transfer capacitance        |                                                                       |             | 6           |             | pF         |
| $E_{oss}$           | 电容存储能量<br>$C_{oss}$ Stored Energy             |                                                                       |             | 92          |             | $\mu J$    |
| $R_{Gint}$          | 内部栅极电阻<br>Internal gate resistor              | $V_{GS}=0V$                                                           |             | 4           |             | $\Omega$   |
| $Q_{gs}$            | 栅源电荷<br>Gate to source charge                 | $I_D=20A, V_{DS}=600V, V_{GS}=-3/+15V$                                |             | 10          |             | nC         |
| $Q_{gd}$            | 栅漏电荷<br>Gate to drain charge                  |                                                                       |             | 37          |             | nC         |
| $Q_g$               | 总栅极电荷<br>Total gate charge                    |                                                                       |             | 50          |             | nC         |
| $V_{SD}$            | 二极管正向电压<br>Diode forward voltage              | $I_{SD}=20A, V_{GS}=-3V$                                              |             | 5.8         |             | V          |
|                     |                                               | $I_{SD}=20A, V_{GS}=-3V, T_{vj}=175\text{ }^{\circ}\text{C}$          |             | 5.4         |             | V          |

**注意:** 1.(\*1)表示最长持续时间 10min(\*1) ) indicates 10min, maximum);

**Note:** 2.(\*2)表示做过预处理后的测试值(\*2) indicates  $V_{GS(th)}$  is preprocessed).

**工艺参数值****Mechanical Parameters**

|                                                                |                                                                                                                          |                 |
|----------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------|-----------------|
| 芯片尺寸<br>Chip size                                              | 3.43×3.43                                                                                                                | mm <sup>2</sup> |
| 源极键合区尺寸(不包含开尔文源级)<br>Source pad size (excl. Kelvin Source pad) | 2×(1.24×1.68)                                                                                                            | mm <sup>2</sup> |
| 栅极键合区尺寸<br>Gate pad size                                       | 0.8×0.8                                                                                                                  | mm <sup>2</sup> |
| 总面积<br>Area total                                              | 11.76                                                                                                                    | mm <sup>2</sup> |
| 厚度<br>Thickness                                                | 360±25                                                                                                                   | μm              |
| 晶圆尺寸<br>Wafer size                                             | 150                                                                                                                      | mm              |
| 每片晶圆上最大芯片数<br>Max. possible chips per wafer                    | 1300                                                                                                                     |                 |
| 正面金属<br>Frontside (Source and Gate) metal                      | Al(4μm)                                                                                                                  |                 |
| 背面金属<br>Backside (Drain) metal                                 | Ti:Ni:Ag (0.05:0.5:1μm)                                                                                                  |                 |
| 正面钝化<br>Passivation frontside                                  | Polyimide                                                                                                                |                 |
| 建议存储环境<br>Recommended storage environment                      | 存储在原始容器中, 23°C 干燥氮气柜小于 6 个月<br>Store in original container, in dry nitrogen, <6 months at an ambient temperature of 23°C |                 |

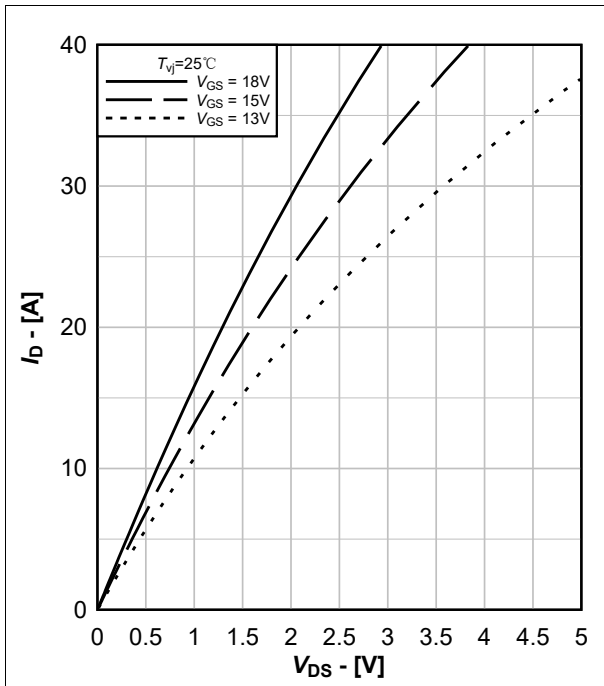


图 2. 输出特性典型曲线,  $I_D = f(V_{DS})$ ,  $T_{vj} = 25\text{ }^{\circ}\text{C}$

Fig.2 Typical output characteristics,  $I_D = f(V_{DS})$ ,  $T_{vj} = 25\text{ }^{\circ}\text{C}$

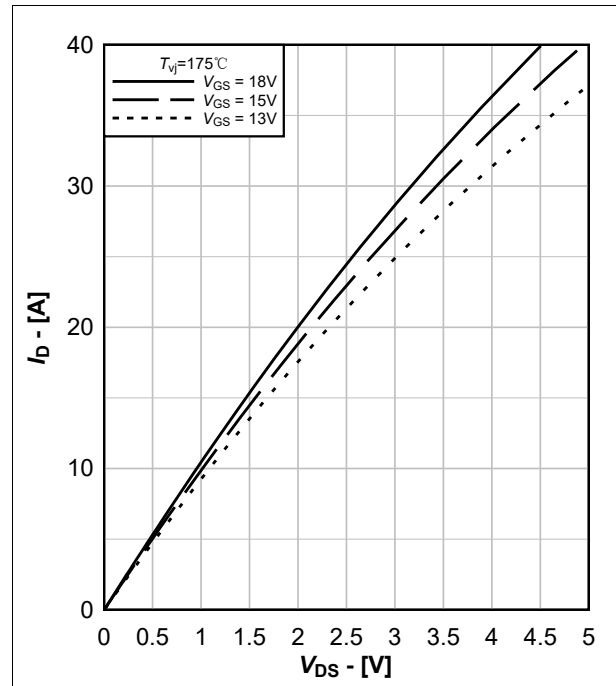


图 3. 输出特性典型曲线,  $I_D = f(V_{DS})$ ,  $T_{vj} = 175\text{ }^{\circ}\text{C}$

Fig.3 Typical output characteristics,  $I_D = f(V_{DS})$ ,  $T_{vj} = 175\text{ }^{\circ}\text{C}$

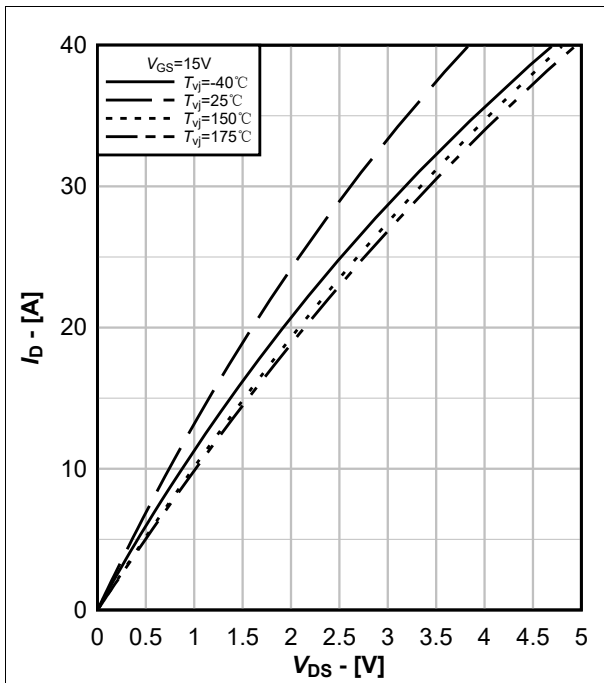


图 4. 输出特性典型曲线,  $I_D = f(V_{DS})$

Fig.4 Typical output characteristics,  $I_D = f(V_{DS})$

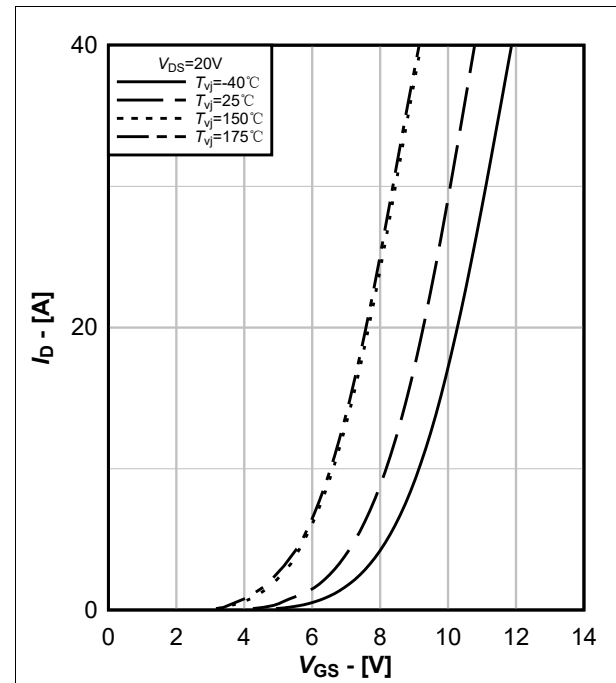
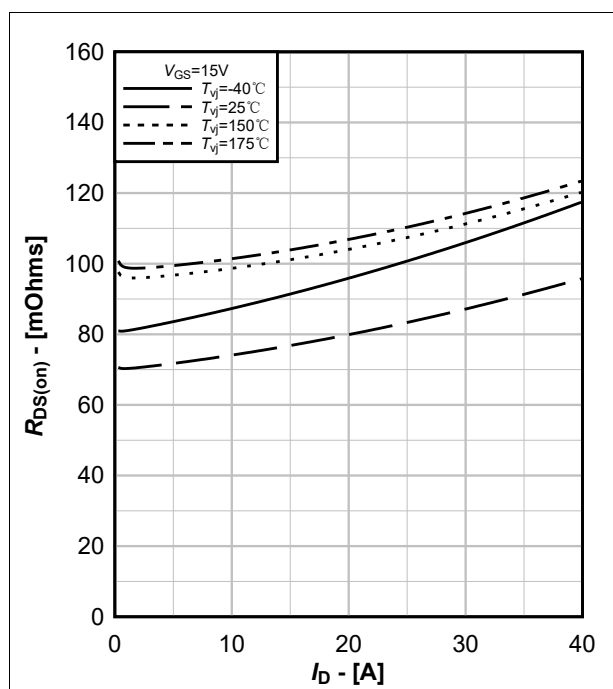
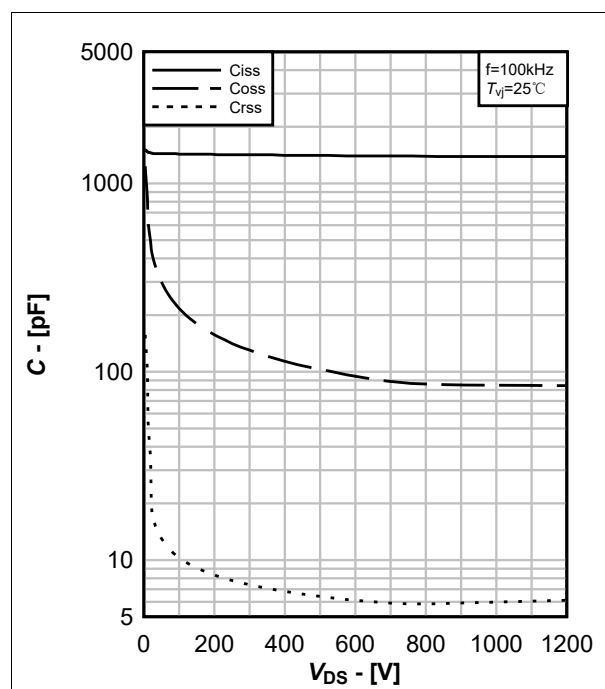
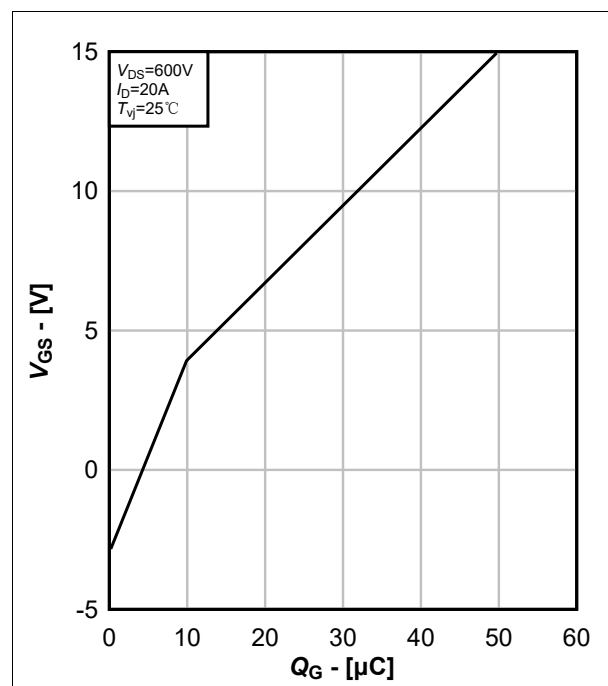
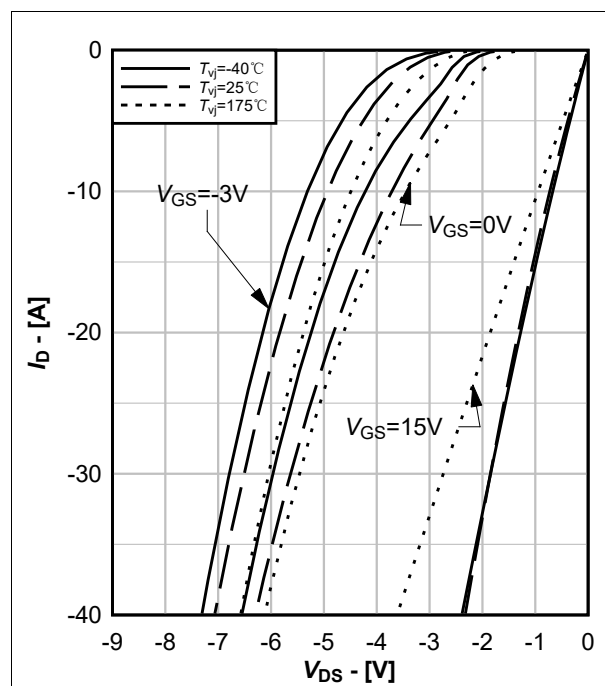
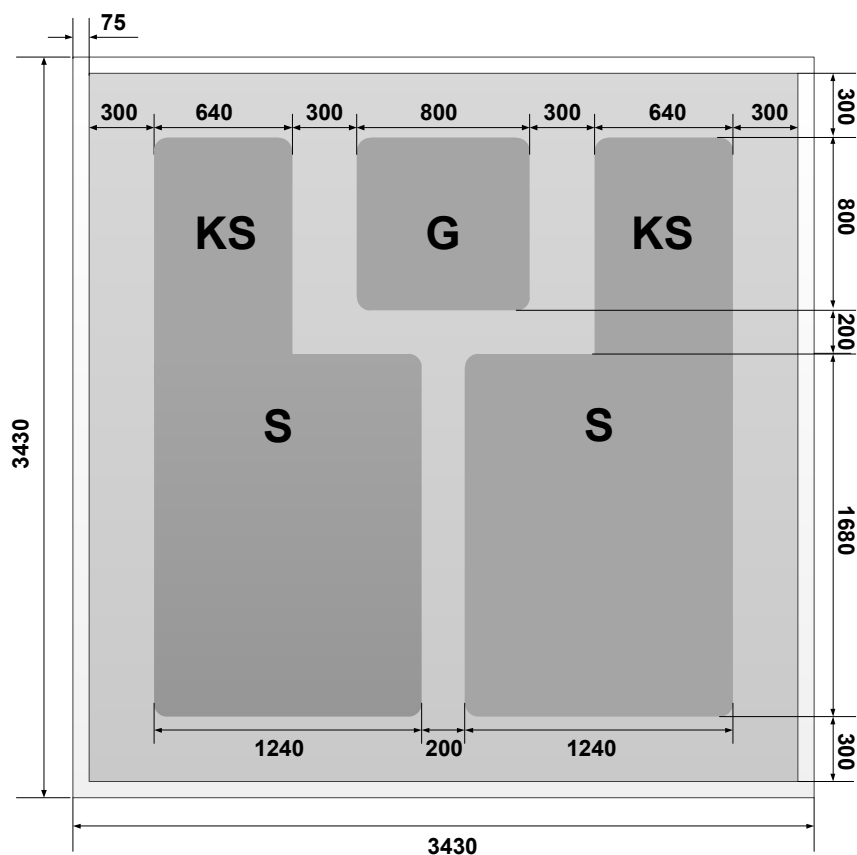


图 5. 传输特性典型曲线,  $I_D = f(V_{GS})$

Fig.5 Typical transfer characteristics,  $I_D = f(V_{GS})$

图 6. 导通电阻典型曲线,  $R_{DS(on)} = f(I_D)$ Fig.6 Typical On-Resistance characteristics,  $R_{DS(on)} = f(I_D)$ 图 7. 电容特性典型曲线,  $C = f(V_{DS})$ Fig.7 Typical capacity characteristic,  $C = f(V_{DS})$ 图 8. 栅极电荷特性典型曲线,  $V_{GS} = f(Q_G)$ Fig.8 Typical gate charge characteristic,  $V_{GS} = f(Q_G)$ 图 9. 体二极管及第三象限输出特性典型曲线,  $I_D = f(V_{DS})$ Fig.9 Typical body diode output and 3rd quadrant characteristic,  $I_D = f(V_{DS})$



S=源极 G=栅极 KS=开尔文源极 单位：微米

S=Source G=Gate KS=Kelvin Source Unit:  $\mu\text{m}$

图 10. 芯片外观尺寸

Fig. 10 Chip drawing

株洲中车时代半导体有限公司

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